

REMARKS

Claims 6-26 have been examined, with all claims rejected under 35 U.S.C. 102(b) as being anticipated by Prabhu (U.S. Patent No. 6,791,072). Applicant respectfully traverses this rejection for the following reasons.

Amended independent claim 6 recites “An integrated circuit arrangement comprising a nonplanar substrate in which an integrated circuit is formed on a side of the substrate arranged on a carrier and on a same side of the substrate facing the carrier, wherein the carrier is produced from a chemically resistant material.”

The amendments to the claims should be entered as they should not require further search and/or consideration. The Examiner stated in the Advisory Action dated June 10, 2009, that she understood Applicant’s intention to claim that the integrated circuit is formed on the carrier side of the substrate.

As asserted previously, this feature is advantageous for the reasons stated in paragraph [0017] of the published application. More specifically, manipulating or analyzing the integrated circuit causes the carrier 4 to be removed, so that the underlying layers of the substrate 2 become accessible. As a result of the fact that the carrier 4 is produced from a chemically resistant material, it cannot be removed by etching. The curved carrier 4 defines the substrate curvature, so that the substrate 2 can no longer be changed to a planar shape. The carrier 4 could thus be removed only by means of a grinding process which then also simultaneously destroys the substrate layers which are arranged underneath the carrier 4.

In contrast, Prabhu’s optical circuitry 702 is formed on a side of substrate 701 that is opposite to the side arranged on rigid support 703. See Prabhu, Figure 7(c). Optical circuitry 702 is therefore much more easily accessible, via window 705a, than the integrated circuit of the claimed invention.

Thus, independent claim 6, along with dependent claims 7-21, is patentable over Prabhu for at least this reason.

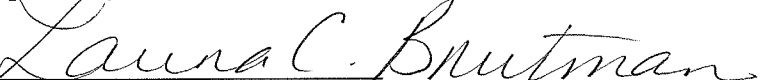
Similarly, independent claim 22 recites "An integrated circuit arrangement comprising a curved substrate having an integrated circuit formed in the substrate arranged on a carrier, wherein the integrated circuit is formed in a side of the substrate facing the carrier, and the carrier is produced from a chemically resistant material." Thus independent claim 22, along with dependent claims 23-26, is patentable over Prabhu for at least this reason.

In view of the above, Applicant believes the pending application is in condition for allowance.

In the event a fee is required or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 50-2215.

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Respectfully submitted,

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